

24830-001 INTERSCALE FLEXIBLE HEAT CONDUCTOR (FHC), 70 MM



KEY FEATURES

Designed for ATX/ITX/Mini ITX & COM using Intel core-iprocessors and AMD processors with the following sockets: Intel: LGA775, LGA1150, LGA1155, LGA1366, LGA1366, LGA2011; AMD: AM2, AM2(+), AM3, AM3(+), FM1, FM2, FM2(+)

Compatible with Interscale C enclosures

Provides industry leading conduction cooling performance, 70% improvement over current conduction cooling methods

Conductor block expands/contracts vertically to compensate fortolerance stack up and optimizes surface contact and pressurealong the thermal path; eliminates the need for a thermal gappad

Secured to PCB with mounting brackets, sold separately

PRODUCT ATTRIBUTES

Product Type: Conductor Block

Product Family: Interscale

Type: Heat Conductor

Works With: Cases

Package Quantity: 1

Depth: 50 mm

Width: 50 mm

ADDITIONAL PRODUCT DETAILS

Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad.

Please order the mounting bracket (Intel or AMD, listed under accessories) to assemble the FHC to the board.

CERTIFICATIONS



North America

All locations +1.763.422.2661 Chat with us: schroff.nyent.com

Europe

Straubenhardt, Germany +49.7082.794.0 Betschdorf, France +33.3.88.90.64.90 Warsaw, Poland +48.22.209.98.35 Assago, Italy +39.02.932.7141 Chat with us: schroff.nvent.com

nVent.com

Asia

Shanghai, China +86.21.2412.6943 Qingdao, China +86.532.8771.6101 Singapore +65.6768.5800 Shin-Yokohama, Japan +81.45.476.0271 Chat with us: schroff.nvent.com

Middle East & India

Dubai, United Arab Emirates +971.4.378.1700 Bangalore, India +91.80.6715.2001 Istanbul, Turkey +90.216.250.7374 Chat with us: schroff.nvent.com



Our powerful portfolio of brands:

CADDY ERICO HOFFMAN RAYCHEM SCHROFF TRACER